2012 2nd IEEE CPMT Symposium Japan

Kyoto, Japan
10 – 12 December 2012

IEEE Catalog Number: CFP12PWJ-PRT
ISBN: 978-1-4673-2654-4

Program Session

December 10, 2012

Room A

13:00-14:40 Session 1: High-Speed Optical Transceiver

Session Chair: Shigeru Nakagawa (IBM Research - Tokyo)
Fumio Koyama (Tokyo Institute of Technology)

1-1 **(Invited) Integration Technologies and Packaging for Efficient Si Photonics Links** **N/A**
Kannan Raj (Photonics Research Director, Oracle Labs)

1-2 **High-stability 25 Gb/s optical transceiver module with flexible polymer wave guide for optical interconnection** **1**
Naoki Matsushima[1], Toshiaki Takai[1], Daichi Kawamura[2], Yasunobu Matsuoka[2], Yong Lee[2,3], Norio Chujo[1], Takashi Takemoto[2,3], Hiroki Yamashita[2,3], Toshiki Sugawara[2], Toru Yazaki[1] and Shinji Tsuji[2,3] (Yokohama Research Laboratory, Hitachi, Ltd.[1], Central Research Laboratory, Hitachi, Ltd.[2], Photonics Electronics Technology Research Association[3])

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Nobuyuki Yasui[1], Koji Shibuya[1], Tadashi Murao[1], Takeshi Yamatoya[2], Keita Mochizuki[1] and Hiroshi Aruga[1] (Information technology R & D Center, Mitsubishi Electric Corporation[1], High Frequency & Optical Device Works, Mitsubishi Electric Corporation[2])

15:10-16:50 Session 2: Optical Waveguide Technology

Session Chair: Shigenori Aoki (Fujitsu Laboratories LTD.)
Okihiro Sugihara (Tohoku University)

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Shoji Uegaki (Advanced Semiconductor Engineering)

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Session Chair: Daoguo YANG (Guilin University of Electronic Technology)
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Session Chair: Michitaka Kimura (Renesas Electronics Corporation)
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Yasumitsu Orii (IBM Research Tokyo)

December 11, 2012

Room A

9:00-10:45 Session 9: Devices for Optical Interconnect

Session Chair: Takaaki Ishigure (Keio University)
Tatsuya Yamashita (Toyota Central R&D Labs. Inc.)

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Room B

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15:40-16:55 Session 16: Electric Conductive Material

Session Chair: Phillip Hall (FUJI MACHINE MFG. Co., Ltd.)
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Room C

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Session Chair: Jianqing Wang (Nagoya Institute of Technology)
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Session Chair: Taras Kushta (NEC Corporation)
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15:40-16:55 Session 20: Power Integrity & Signal Integrity

Session Chair: Hideki Osaka (Hitachi Ltd.)
Takashi Harada (NEC Corporation)

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11:00-12:45 Session 22: 3-D Integration by ASET "Dream Chip Project"

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13:40-15:20 Session 23: 3-D Integration by ASET "Dream Chip Project"

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15:40-16:55 Session 24: 3-D Integration by ASET "Dream Chip Project"

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December 12, 2012

Room A

10:00-11:45 Session 25 Interconnect

Session Chair: Yutaka Uematsu (Hitachi Ltd.)
Daisuke Iguchi (Fuji Xerox Co., Ltd.)

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Taiga Fukumori and Daisuke Mizutani (Fujitsu Laboratories Ltd.)

25-2 **Study of the insertion loss of a differential pair of through holes for the 25Gbps serial interconnect** **332**
Go Shinkai, Satoshi Muraoka, Masayoshi Yagu, Yutaka Uematsu and Hideki Osaka (Yokohama Research Laboratory, Hitachi Ltd.)

25-3 **Novel Compact Bandpass Filters for High-Density Packaging Applications** **336**
Taras Kushta and Takashi Harada (Central Research Laboratories, NEC Corporation)

Room B

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Session Chair: Takumi Ueno (Shinshu University)
Yutaka Nomura (Hitachi Chemical Co., Ltd.)

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Masayuki Ohe[1], Tomonori Minegishi[2], Kawasaki Dai[1], Keiko Suzuki[1], Taku Konno[1] and Takahiro Hidaka[2] (Hitachi Chemical DuPont MicroSystems Ltd.[1] , Hitachi Chemical Co., Ltd.[2])

26-2 **Build-up Electrical Insulation Material for High Speed & High-frequency** **343**
Tomoki Kunikawa, Toshiaki Tanaka, Hiroshi Kouyanagi and Kazutaka Shirahase (IM Project, R&D Center, Sekisui Chemical Co., Ltd.)

26-3 **Formation of Circuit Patterns on the Only Modification Area Using Selective Electroless Deposition** **347**
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Room C

10:00-11:45 Session 27: Component & Circuit

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Takashi Harada (NEC Corporation)

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Kohei Takada, Daijiro Ishibashi and Nobuhiro Kuga (Faculty of Engineering, Yokohama National University)

27-2 **Influence of a foam supporter on passive intermodulation measurement using standing-wave coaxial tube method** **355**
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27-3 **Fundamental Study of Direct Current Resistance Effect on Transmission Line Characteristics** **359**
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Session Chair: Kishio Yokouchi (Fujitsu Interconnect Technologies Ltd.)
Atsushi Nakamura (Renesas Electronics Corporation)